

Appl. No. 09/915,919
Amdt. dated June 8, 2005
Reply to Office action of Mar. 10, 2005

Amendments to the Drawings:

The attached sheet of drawings includes changes to Figs. 1-3, replacing the original sheet including Figs. 1-3. In Figure 3, previously omitted "buried ground plate" has been added.

Attachment: Replacement Sheet
Annotated Sheet Showing Changes

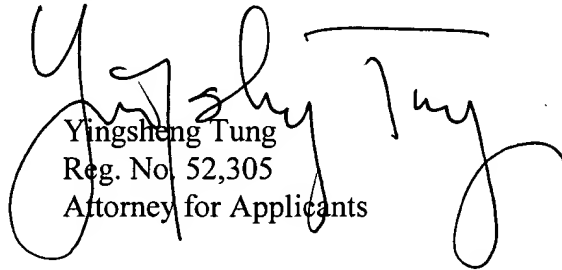
Remarks

Applicants thank Examiner Nguyen for the careful examination of this application and for allowing the pending claims. In response to the Office action, applicants cancel claims 14-19; amends claims 7, 8, and 10. Applicants also amend drawing figure 3 to depict one exemplary buried ground plate in the interposer, as claimed in claim 6.

Regarding claims 9 and 21, applicants respectfully submit that as explained in the second paragraph on page 14 of the original specification, software may be used to enable a computer controlled laser to generate a desired pattern of conductive leads on the surface of a surface of an interposer. In order to describe the invention more clearly without narrowing the scope of the claims, however, applicants amend claim 9 and 21 as shown in the list of claims.

Applicants respectfully submit that, as amended, this application is in allowable form and the amended claims overcome the objections in the Office action. Applicants respectfully request timely allowance of all pending claims.

Respectfully submitted,


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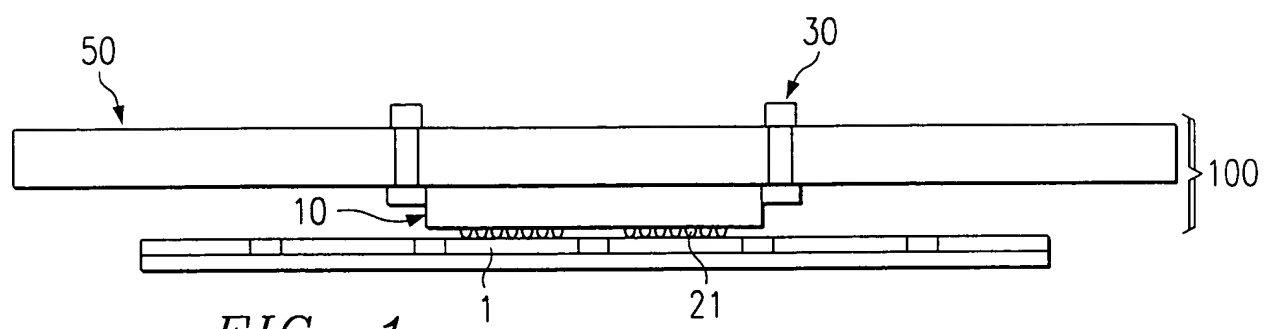


FIG. 1

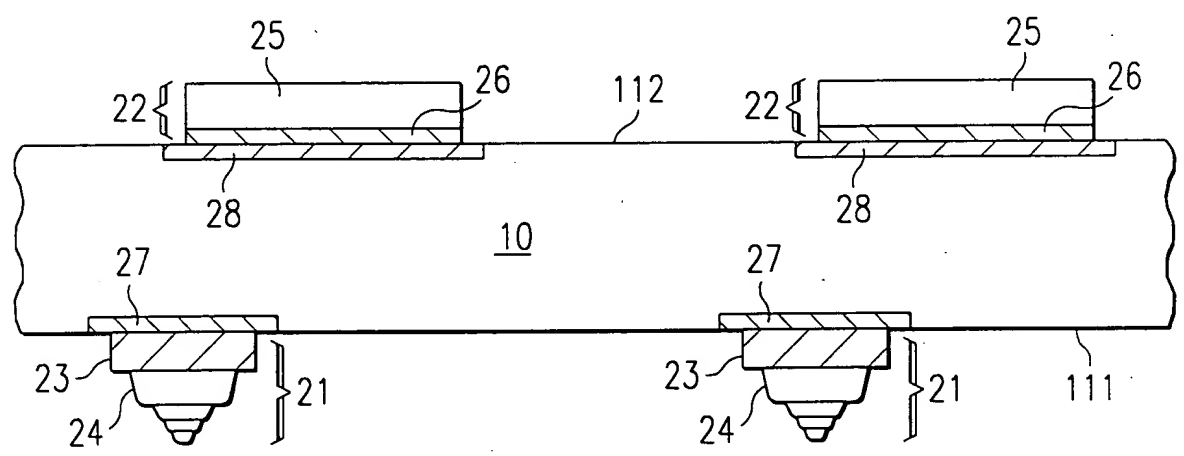


FIG. 2

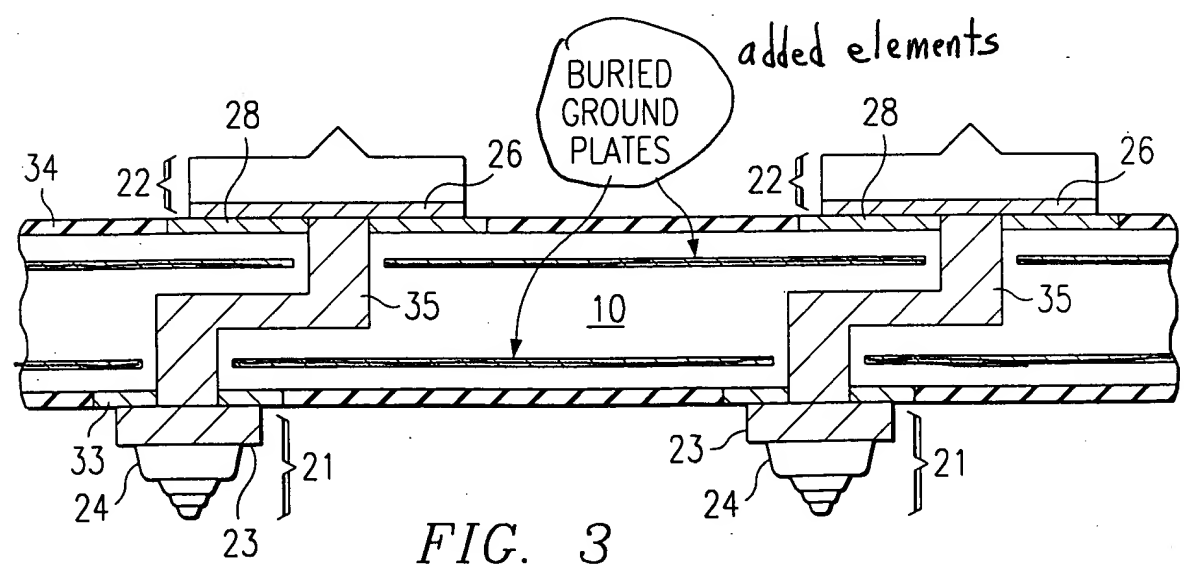


FIG. 3